



# Calculation of the mobility in Al<sub>2</sub>O<sub>3</sub>/GaN electron channel: Effect of p-doping and comparison with experiments<sup>☆</sup>

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## ABSTRACT

The low field electron mobility of Al<sub>2</sub>O<sub>3</sub>/GaN channel is calculated using a semi-classical framework. The aim is to obtain the mobility as a function of the electron sheet density and the temperature, with different p-doping conditions in GaN, and to compare it with our measurements on various samples. The scattering with bulk and surface phonons is taken into account. Scattering with dopants, interface charges, neutral impurities and interface roughness is also included in an attempt to account for experimental observations. We found that, when bringing p-dopants closer to the Al<sub>2</sub>O<sub>3</sub>/GaN interface, the mobility decreases mainly because the electron channel is more confined and located closer to Al<sub>2</sub>O<sub>3</sub>, thereby enhancing scattering mechanisms located near the Al<sub>2</sub>O<sub>3</sub>/GaN interface. Our results suggest that most of transport limitations come from Al<sub>2</sub>O<sub>3</sub> oxide.

## 1. Introduction

Due to their wide band gap, high breakdown voltage and good transport properties, GaN is an attractive material for high power/frequency applications. Normally-OFF operations can be achieved with MOS-HEMT architecture which is considered as a promising candidate thanks to its low leakage current [1]. In this context, investigating the transport limitations in Al<sub>2</sub>O<sub>3</sub>/GaN channel is important for optimizing the performances but also to feed TCAD simulations with physical models. Moreover, the effect of p-doping of GaN on the electron mobility in Al<sub>2</sub>O<sub>3</sub>/GaN channel has not been reported in literature.

## 2. Experimental setup

GaN is grown on p-type Si substrate using MOCVD deposition. Transition layers are used for strain management and are followed by a thick and highly Carbon-doped GaN layer (GaN:C, [C] ≈ 2.10<sup>19</sup> cm<sup>-3</sup>) to ensure vertical insulation. Then, the GaN channel has either no intentional doping (NID) or is p-doped with Magnesium (Mg). Al<sub>2</sub>O<sub>3</sub> oxide is 30 nm thick and is deposited by Atomic Layer Deposition method. The four samples measured are shown in Fig. 1a. Sample A has no Mg-doping and samples B, C and D only differ by the Mg-doping profile  $N_A(z)$  below the Al<sub>2</sub>O<sub>3</sub>/GaN interface (Fig. 1b). Measurements of the low field mobility as a function of the electron sheet density

$n_s$  for temperatures ranging from 298 K to 423 K have been performed with split-CV method on transistors with long gate length  $L_G = 60 \mu\text{m}$  to avoid any effect of access resistances. The electron sheet density is obtained by integrating the gate-to-channel capacitance  $C_{GC}(V_G)$  measurement:

$$n_s(V_G) = \frac{1}{e} \int_0^{V_G} C_{GC}(V) dV \quad (1)$$

The effective mobility is then obtained using the split-CV formula:

$$\mu_{eff} = \frac{L_G}{e W_G V_D} \frac{I_D(V_G)}{n_s(V_G)} \quad (2)$$

where  $V_D$  is set to 50 mV to be in low field regime and the gate width  $W_G$  is 200  $\mu\text{m}$ . The drain current  $I_D(V_G)$  and the gate-to-channel capacitance  $C_{GC}(V_G)$  measurements are simultaneous and fast (the total measurement time is 0.7 ms) to avoid gate voltage stress. The protocol is explained in detail and validated in [2].

## 3. Calculations

The electron density and potential along the stacks are obtained with self-consistent 1D Schrödinger–Poisson simulations for the  $\Gamma$ -valley electrons under the effective mass approximation for non-parabolic and spherical energy bands ( $m_{\Gamma M} = m_{\Gamma K} \approx m_{\Gamma A}$  [3]). Non-parabolic

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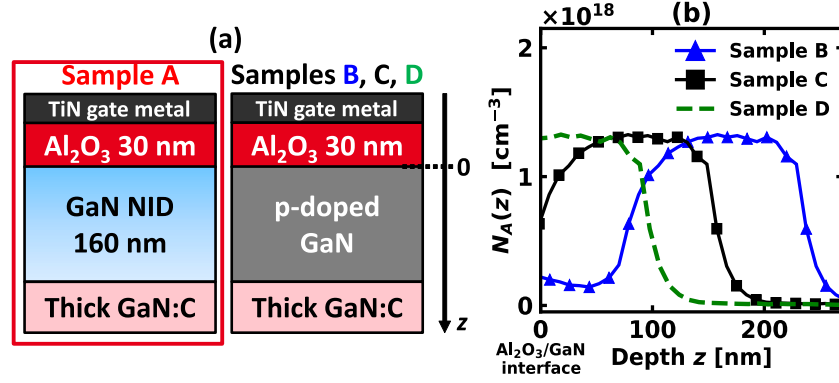


Fig. 1. (a) Stacks studied (NID: Not intentionally doped). (b)  $N_A(z)$  profiles (experimental SIMS data). As can be seen from the  $N_A(z)$  profiles, p-doped GaN is approximately 260 nm thick in sample B, 160 nm thick in sample C, and 100 nm thick in sample D.

corrections are included using Jin et al. model [4]. Incomplete ionization model is used to properly account for the Fermi level in GaN:C. Carbon impurities are assumed as deep acceptors (0.8 eV above the valence band maximum VBM) partially compensated by shallow donors (0.1 eV below the conduction band minimum) [5]. This leads to a Fermi level pinning at 0.84 eV from the VBM in GaN:C which is consistent with experimental findings [6]. The p-doping is included by using  $N_A(z)$  profiles (Fig. 1b) in the simulations, also accounting for incomplete ionization with an Mg acceptor level located at 0.16 eV above the VBM [7]. The framework used to calculate the mobility is based on the linearized 2D Boltzmann transport equation and on Fermi's golden rule. It has been massively used in MOS inversion layers [8–10]. The originality of our study comes from applying this framework in  $\text{Al}_2\text{O}_3/\text{GaN}$  channel, from including neutral impurities and from emphasizing the effect of p-doping.

The scattering rates are obtained with Fermi's golden rule. For the elastic scattering mechanism  $s$ , the scattering rate of an electron of subband  $i$  and energy  $E$  is given by:

$$\frac{1}{\tau_i^s(E)} = A \frac{m_F}{2\pi\hbar^3} \sum_{j|E_j < E} (1 + 2\alpha(E - U_j)) \times \int_0^{2\pi} d\theta (1 - \cos\theta) |M_{ij}^s(q)|^2 \quad (3)$$

where  $A$  is the area,  $\alpha$  is the non parabolicity factor and  $U_j$  is the expected value of the potential energy of subband  $j$  in the confinement direction  $z$  [4].  $\theta$  is the angle between  $\mathbf{k}$  and  $\mathbf{k}'$  which are the 2D wavevectors before and after the scattering event, respectively, and  $q = |\mathbf{k} - \mathbf{k}'|$ .  $M_{ij}^s$  is a scattering matrix element, obtained from the 2D Fourier transform of the scattering potential ( $V^s(q, z)$ ) and the wavefunctions ( $\psi$ ) [9]. For inelastic scatterings (optical phonons), the scattering rates are given by:

$$\frac{1}{\tau_i^{POP,SO}(E)} = A \frac{m_F}{2\pi\hbar^3} \sum_{j|E_j < E \pm \hbar\omega} \frac{1 - f(E \pm \hbar\omega)}{1 - f(E)} (1 + 2\alpha(E \pm \hbar\omega - U_j)) \times \int_0^{2\pi} d\theta (1 - \cos\theta) |M_{ij}^{POP,SO}(q)|^2 \quad (4)$$

where  $\hbar\omega$  is the energy of the optical phonons,  $+$  is for the absorption and  $-$  is for the emission of a phonon. After calculating the scattering rates of all mechanisms considered, the total scattering rate is obtained using Matthiessen's rule ( $1/\tau_i(E) = \sum_s 1/\tau_i^s(E)$ ). The mobility is finally computed with "Kubo–Greenwood" formula:

$$\mu = \frac{-e}{\pi\hbar^2 n_s} \sum_i \int_{E_i}^{\infty} dE \tau_i(E) \frac{df^0}{dE} \frac{(E - E_i + \alpha(E - U_i)^2)}{1 + 2\alpha(E - U_i)} \quad (5)$$

Screening is included by dividing the diagonal scattering matrix elements by the magnitude of the scalar dielectric function [9]. The expressions of the scattering matrix elements of acoustic deformation potential (ADP), piezoelectric potential (PE) and polar optical phonons (POP) are taken from [11]. The effect of surface optical (SO) phonons, which arise from transverse polar optical (TO) mode of  $\text{Al}_2\text{O}_3$  and GaN,

Table 1  
Material parameters used in the calculations.

	$E_G$ (eV)	$m_F$ ( $m_0$ )	$\alpha$ ( $\text{eV}^{-1}$ )	$\epsilon^0$ ( $\epsilon_0$ )	$\epsilon^\infty$ ( $\epsilon_0$ )	$\epsilon^{int}$ ( $\epsilon_0$ )	$\omega_{LO}$ (meV)	$\omega_{TO}$ (meV)
GaN <sup>a</sup>	3.4	0.2	0.186	10.28	5.7	–	92	$\omega_{TO3} = 70$
$\text{Al}_2\text{O}_3^b$	7.0	0.4	–	9	3.2	7.27	–	$\omega_{TO1,TO2} = 48, 71$

<sup>a</sup>  $E_G$ ,  $m_F$  from [3].  $\epsilon^0$ ,  $\epsilon^\infty$  from [13] and optical modes  $\omega$  from [14].

<sup>b</sup>  $E_G$ ,  $\epsilon^0$  from [15], effective mass from [16] and the rest from [12,17].

( $\epsilon^{int} \approx \epsilon^\infty (\omega_{TO2}/\omega_{LO})^2$ ) as explained in [12] with  $\omega_{LO}$  taken from [17]).

is estimated following the method of Fischetti et al. [12]. Calculations are done assuming an infinite oxide (justified because the oxide is 30 nm thick) and neglecting the coupling with 2DEG's plasmon. Two TO frequencies are considered in  $\text{Al}_2\text{O}_3$  ( $\omega_{TO1}$  and  $\omega_{TO2}$ ) and one in GaN ( $\omega_{TO3}$ ). Their value is given in Table 1. Since  $\omega_{TO2}$  is very close to  $\omega_{TO3}$ , we assumed  $\omega_{TO3} = \omega_{TO2}$  in the calculations. Two SO modes are obtained and their frequency can be expressed as follows:

$$\omega_{SO1}^2 = \omega_{TO1}^2 \frac{\epsilon_{ox}^0 + \epsilon_{GaN}^0}{\epsilon_{ox}^{int} + \epsilon_{GaN}^0}, \quad \omega_{SO2}^2 = \omega_{TO2}^2 \frac{\epsilon_{ox}^{int} + \epsilon_{GaN}^0}{\epsilon_{ox}^\infty + \epsilon_{GaN}^\infty} \quad (6)$$

where  $\epsilon_0$ ,  $\epsilon_{int}$  and  $\epsilon_\infty$  refer to the static, intermediate and dynamic permittivity. To calculate the amplitude of these modes, we followed the procedure outlined in [12], that is, for each phonon mode, we calculate the difference in the squared amplitude between the case where the phonon does not respond and the case where the phonon fully responds. Then, the scattering matrix elements can be calculated as in [10].

For SO and POP scatterings, we took into account dynamic screening by including the dependency upon the frequency of phonons in the calculation of the dielectric function as done in [10]. Fig. 2 shows the impact of screening on POP scattering by comparing the POP limited mobility vs  $n_s$  in the unscreened, statically screened and dynamically screened cases. As  $n_s$  increases, the plasma frequency of the 2D electron channel increases and becomes superior to the frequency of POP such that electrons can more effectively screen the time-dependent POP potential. This is why, when  $n_s$  is close to  $10^{13} \text{ cm}^{-2}$ , the dynamic screening case becomes equivalent to the static screening case. This demonstrates the importance of including dynamic screening to accurately assess the POP limited mobility. Fig. 3 compares all the phonons limited mobilities, highlighting the dominance of POP. The total phonon limited mobility is also shown and it is slightly above  $1000 \text{ cm}^2 \text{ V}^{-1} \text{ s}^{-1}$ , which is much higher than the experimental effective mobility, indicating that phonons are far from being the main scattering mechanisms limiting transport.

To account for experimental observations, scattering with dopants, interface charges (ICs) and interface roughness (IR) is included following the approaches which have been employed in bulk MOSFET [9].

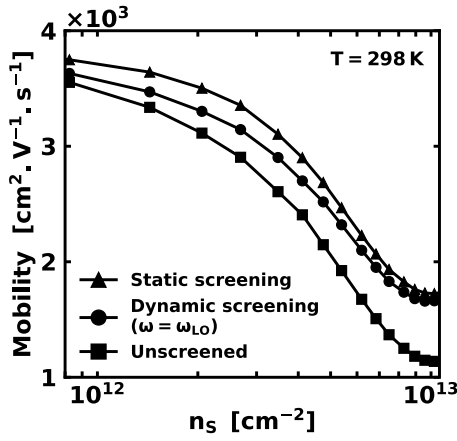


Fig. 2. POP limited mobility vs.  $n_s$ . Dynamic screening is compared to the unscreened and statically screened cases. (Sample A).

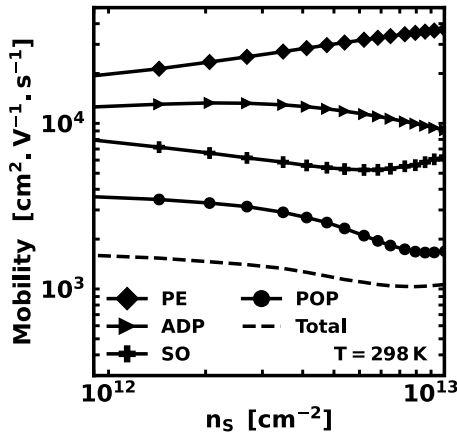


Fig. 3. All phonons limited mobility vs.  $n_s$ . ADP and PE material properties are taken from [11]. (Sample A).

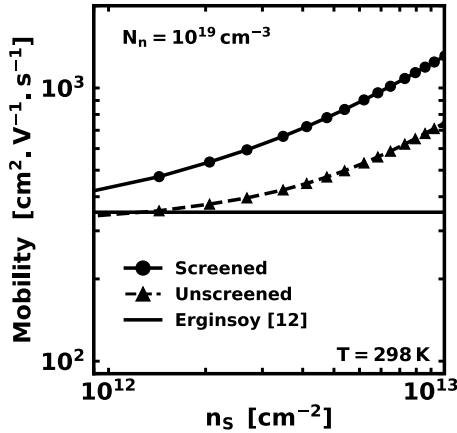


Fig. 4. Neutral impurities limited mobility vs.  $n_s$  for a uniform density of neutral impurities  $N_n = 10^{19} \text{ cm}^{-3}$  in GaN.

The squared magnitude of the interface roughness scattering matrix elements are obtained from the generalized Prange-Nee term [9]:

$$\left| M_{ij}^{IR}(q) \right|^2 = \frac{\left| \int dz \psi_i(z) \psi_j(z) \left( -e \frac{d\phi}{dz} \right) + (E_i - E_j) \int dz \psi_i(z) \frac{d\psi_j(z)}{dz} \right|^2}{|\Delta(q)|^2} \quad (7)$$

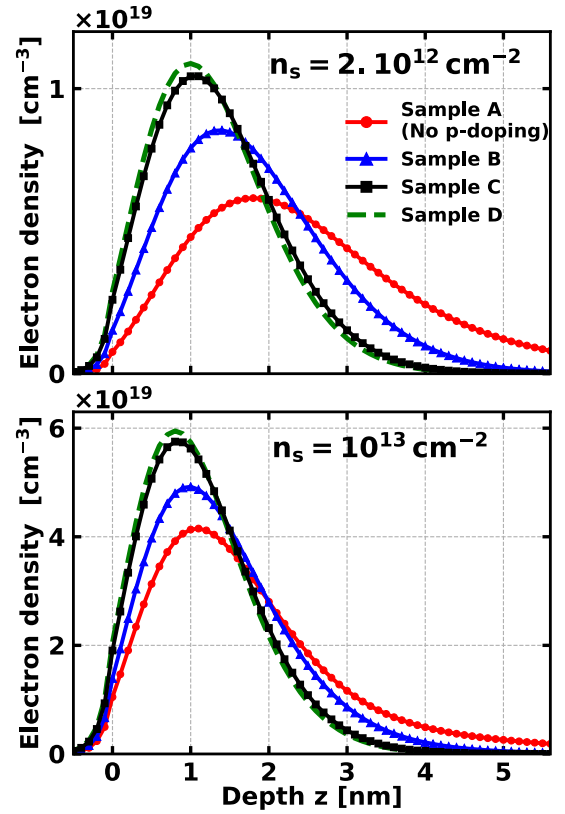


Fig. 5. Electron density vs. depth  $z$  calculated for the four samples for two different  $n_s$ . Top:  $n_s = 2.10^{12} \text{ cm}^{-2}$  and bottom:  $n_s = 10^{13} \text{ cm}^{-2}$ .  $N_A(z)$  profiles in Fig. 1b are used in the calculations.

where  $\phi$  is the potential and  $\psi_i, \psi_j$  are the wavefunctions of subbands  $i$  and  $j$ , respectively. The roughness is described with an exponential spectrum,  $|\Delta(q)|^2$  is given by [9]:

$$|\Delta(q)|^2 = \frac{1}{A} \pi \Delta_{sr}^2 \Lambda_{sr}^2 \left( 1 + \frac{q^2 \Lambda_{sr}^2}{2} \right)^{-3/2} \quad (8)$$

where  $\Delta_{sr}$  is the root-mean-square and  $\Lambda_{sr}$  is the correlation length. The scattering with neutral impurities (NIs) is also included: in addition to non ionized dopants, NIs are added near the  $\text{Al}_2\text{O}_3/\text{GaN}$  interface, which will yield a better agreement with experiments. To include this scattering, we use the hydrogen potential scaled by the effective mass and dielectric constant of the medium, as done by Erginsoy [18]. But Erginsoy model is made for 3D transport. In the case of a 2D electron channel, one must consider the non-uniformity of the electron density and the screening produced by the 2D electron gas. We did so by calculating the 2D Fourier transform of hydrogen potential, using the 3D Fourier transform given in [19]. This yields:

$$V_h(q, z) = \frac{-e}{2\epsilon \sqrt{4a_B^{-2} + q^2}} \left( 1 + \frac{2a_B^{-2}}{4a_B^{-2} + q^2} + \frac{2a_B^{-2}}{\sqrt{4a_B^{-2} + q^2}} |z| \right) \times \exp \left( -\sqrt{4a_B^{-2} + q^2} |z| \right) \quad (9)$$

where  $a_B = (4\pi\epsilon\hbar^2)/(m_I e^2)$  is the effective Bohr radius. From this potential, the screened scattering matrix elements can be computed the same way as for other mechanisms. The resulting mobility for a uniform distribution of NIs in GaN is shown in Fig. 4. At low  $n_s$ , the calculations tend to Erginsoy model but increasing  $n_s$  enhances screening and reduces the effect of background NIs (NIs located below the channel), leading to an increased mobility. In the following calculations, we will consider an inhomogeneous distribution of NIs.

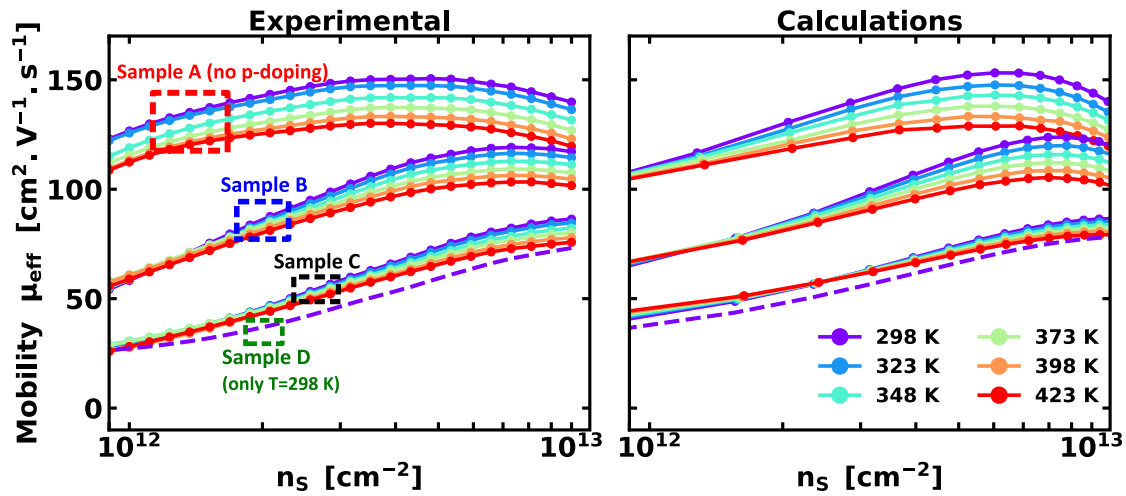


Fig. 6.  $\mu_{eff}$  vs  $n_s$  from 298 K to 423 K (Experimental (left) and calculations (right)). In the calculations we used: a density of interface charges  $\sigma_{\text{Al}_2\text{O}_3/\text{GaN}} = 1.42 \cdot 10^{13} \text{ cm}^{-2}$ , a Gaussian distribution of neutral impurities centered at  $\text{Al}_2\text{O}_3/\text{GaN}$  interface with an integrated density  $N_n^+ = 7 \cdot 10^{12} \text{ cm}^{-2}$  and for interface roughness, we employed an exponential spectrum with a correlation length  $\Lambda_{sr} = 1.5 \text{ nm}$  and a root-mean-square  $\Delta_{sr} = 0.6 \text{ nm}$ . These parameters are not changed between samples.  $N_A(z)$  profiles in Fig. 1b are used in the calculations.

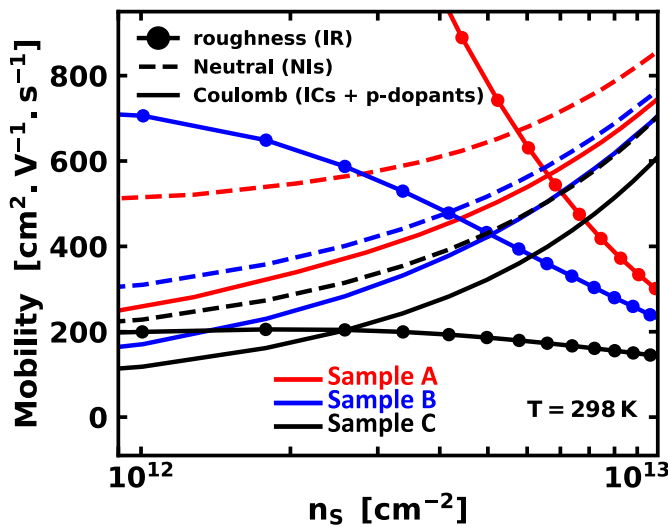


Fig. 7. Interface roughness, Coulomb and neutral impurities scattering limited mobility vs  $n_s$  for samples A, B, C. Increasing the level of p-doping and its proximity to the interface induces more confinement and enhances the effects of these scatterings.  $N_A(z)$  profiles in Fig. 1b are used in the calculations.

#### 4. Comparison with experiments

In Fig. 6(left), the experimental effective mobility  $\mu_{eff}$  is plotted against  $n_s$  at different temperatures in the four samples. The only way to account for the low effective mobility and for the detrimental effect of p-doping on the mobility is by reinforcing scattering mechanisms located near the interface. Among those are ICs and IR scattering. A high ICs density with the same sign would induce a high  $V_{TH}$  shift. Alternative defects which do not affect the  $V_{TH}$  are NIs, hence we assume a part of the defects located near the interface to be NIs. A Gaussian distribution of NIs centered at  $\text{Al}_2\text{O}_3/\text{GaN}$  interface and with a standard deviation  $\sigma = 1.5 \text{ nm}$  has been considered in the calculations. In Fig. 6,  $\mu_{eff}$  vs  $n_s$  is calculated from 298 K to 423 K for the four samples and is compared to experimental measurements. With the same set of parameters, a good agreement is obtained for all samples, especially at high  $n_s$  but a high density of ICs and NIs was required to account for the low value of  $\mu_{eff}$ . The ICs/NIs proportion can be modified without significantly changing the results. By bringing p-dopants closer to the

interface (see  $N_A(z)$  in Fig. 1b),  $\mu_{eff}$  decreases because, as shown in Fig. 5, electrons are closer to  $\text{Al}_2\text{O}_3$ , thereby increasing the effect of IR, ICs and NIs. This is demonstrated in Fig. 7 where the mobility limited by these scattering mechanisms is shown for 3 samples. We can notice that p-doping has a huge impact on IR limited mobility especially as  $n_s$  decreases. In sample A, IR limited mobility is important mostly at high  $n_s$ , while in sample C, it is important in the whole  $n_s$  range. This is because, as depicted in Fig. 5, at low  $n_s$ , the electron channel of sample A is away from the interface and then, at high  $n_s$ , it gets much closer to the interface due to the high gate voltage applied. In contrast, in sample C, the electron channel is always confined and close to the interface (both at high and low  $n_s$ ) due to the high level of p-doping. This is why the IR limited mobility of sample C is important in the whole  $n_s$  range. However, IR limited mobility cannot explain on its own the reduction in mobility induced by p-doping. ICs and NIs limited mobilities are also reduced by p-doping and their effect on transport is important, especially at low  $n_s$  (see Fig. 7). The Coulomb and neutral defects scattering is mostly due to the high density of interface defects (ICs and NIs). The scattering by p-dopants is negligible compared to the scattering due to interface charges.

#### 5. Conclusion

The mobility in  $\text{Al}_2\text{O}_3/\text{GaN}$  channel was calculated while varying the proximity of GaN p-doping to the interface. The overall good agreement between calculations and experimental data on various samples strongly suggests that the transport limitations mostly come from interface roughness and from “defects” located near  $\text{Al}_2\text{O}_3/\text{GaN}$  interface. We illustrated the effect of interface charges and neutral impurities in this study but the exact origin of these “defects”, most likely due to the high- $\kappa$   $\text{Al}_2\text{O}_3$  oxide, needs to be further investigated.

#### Declaration of competing interest

The authors declare that they have no known competing financial interests or personal relationships that could have appeared to influence the work reported in this paper.

#### Data availability

Data will be made available on request.

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